

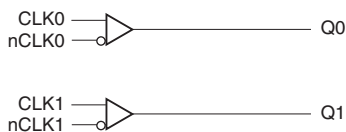
## GENERAL DESCRIPTION

The 83023I is a dual, 1-to-1 Differential-to-LVCMOS Translator/Fanout Buffer. The differential inputs can accept most differential signal types (LVDS, LVHSTL, LVPECL, SSTL, and HCSL) and translate into two single-ended LVCMOS outputs. The small 8-lead SOIC footprint makes this device ideal for use in applications with limited board space.

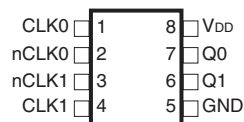
## Features

- Two LVCMOS / LVTTTL outputs
- Two differential CLKx, nCLKx input pairs
- CLK, nCLK pairs can accept the following differential input levels: LVDS, LVPECL, LVHSTL, SSTL, HCSL
- Maximum output frequency: 350MHz (typical)
- Output skew: 60ps (maximum)
- Part-to-part skew: 500ps (maximum)
- Additive phase jitter, RMS: 0.14ps (typical)
- Small 8 lead SOIC package saves board space
- 3.3V operating supply
- -40°C to 85°C ambient operating temperature

## BLOCK DIAGRAM



## PIN ASSIGNMENT



**83023I**

**8-Lead SOIC**

3.8mm x 4.8mm x 1.47mm package body

**M Package**

Top View

**TABLE 1. PIN DESCRIPTIONS**

Number	Name	Type		Description
1	CLK0	Input	Pulldown	Non-inverting differential clock input.
2	nCLK0	Input	Pullup	Inverting differential clock input.
3	nCLK1	Input	Pullup	Inverting differential clock input.
4	CLK1	Input	Pulldown	Non-inverting differential clock input.
5	GND	Power		Power supply ground.
6	Q1	Output		Single clock output. LVCMOS / LVTTTL interface levels.
7	Q0	Output		Single clock output. LVCMOS / LVTTTL interface levels.
8	V <sub>DD</sub>	Power		Positive supply pin.

NOTE: *Pullup* and *Pulldown* refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

**TABLE 2. PIN CHARACTERISTICS**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C <sub>IN</sub>	Input Capacitance			4		pF
C <sub>PD</sub>	Power Dissipation Capacitance (per output)	V <sub>DD</sub> = 3.6V		23		pF
R <sub>PULLUP</sub>	Input Pullup Resistor			51		kΩ
R <sub>PULLDOWN</sub>	Input Pulldown Resistor			51		kΩ
R <sub>OUT</sub>	Output Impedance			7		Ω

# ABSOLUTE MAXIMUM RATINGS

Supply Voltage, $V_{DD}$	4.6V
Inputs, $V_I$	-0.5V to $V_{DD} + 0.5V$
Outputs, $V_O$	-0.5V to $V_{DD} + 0.5V$
Package Thermal Impedance, $\theta_{JA}$	112.7°C/W (0 lfpm)
Storage Temperature, $T_{STG}$	-65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

**TABLE 3A. POWER SUPPLY DC CHARACTERISTICS,  $V_{DD} = 3.3V \pm 0.3V$ ,  $T_A = -40^\circ C$  TO  $85^\circ C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{DD}$	Positive Supply Voltage		3.0	3.3	3.6	V
$I_{DD}$	Positive Supply Current				20	mA

**TABLE 3B. LVCMOS / LVTTTL DC CHARACTERISTICS,  $V_{DD} = 3.3V \pm 0.3V$ ,  $T_A = -40^\circ C$  TO  $85^\circ C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{OH}$	Output High Voltage; NOTE 1		2.6			V
$V_{OL}$	Output Low Voltage; NOTE 1				0.5	V

NOTE 1: Outputs terminated with 50Ω to  $V_{DD}/2$ . See Parameter Measurement Section, 3.3V Output Load Test Circuit.

**TABLE 3C. DIFFERENTIAL DC CHARACTERISTICS,  $V_{DD} = 3.3V \pm 0.3V$ ,  $T_A = -40^\circ C$  TO  $85^\circ C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$I_{IH}$	Input High Current	nCLK0, nCLK1 $V_{IN} = V_{DD} = 3.6V$			5	μA
		CLK0, CLK1 $V_{IN} = V_{DD} = 3.6V$			150	μA
$I_{IL}$	Input Low Current	nCLK0, nCLK1 $V_{IN} = 0V$ , $V_{DD} = 3.6V$	-150			μA
		CLK0, CLK1 $V_{IN} = 0V$ , $V_{DD} = 3.6V$	-5			μA
$V_{PP}$	Peak-to-Peak Input Voltage		0.15		1.3	V
$V_{CMR}$	Common Mode Input Voltage; NOTE 1, 2		GND + 0.5		$V_{DD} - 0.85$	V

NOTE 1: For single-ended applications, the maximum input voltage for CLKx, nCLKx is  $V_{DD} + 0.3V$ .

NOTE 2: Common mode voltage is defined as  $V_{IH}$ .

**TABLE 4. AC CHARACTERISTICS,  $V_{DD} = 3.3V \pm 0.3V$ ,  $T_A = -40^{\circ}C$  TO  $85^{\circ}C$** 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$f_{MAX}$	Maximum Output Frequency			350		MHz
$t_{PD}$	Propagation Delay; NOTE 1		1.8	2.1	2.4	ns
$t_{sk(o)}$	Output Skew; NOTE 2, 4				60	ps
$t_{sk(pp)}$	Part-to-Part Skew; NOTE 3, 4				500	ps
$t_{jit}$	Buffer Additive Phase Jitter, RMS; refer to Additive Phase Jitter Section	100MHz, Integration Range (637kHz-10MHz)		0.14		ps
$t_R$	Output Rise Time	0.8V to 2V	100	250	400	ps
$t_F$	Output Fall Time	0.8V to 2V	100	250	400	ps
odc	Output Duty Cycle	$f \leq 166MHz$	45	50	55	%
		$f > 166MHz$	43	50	57	%

All parameters measured at  $f_{MAX}$  unless noted otherwise. See Parameter Measurement Information.

NOTE 1: Measured from the differential input crossing point to  $V_{DD}/2$  of the output.

NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions.

Measured at  $V_{DD}/2$ . Input clocks are phase aligned.

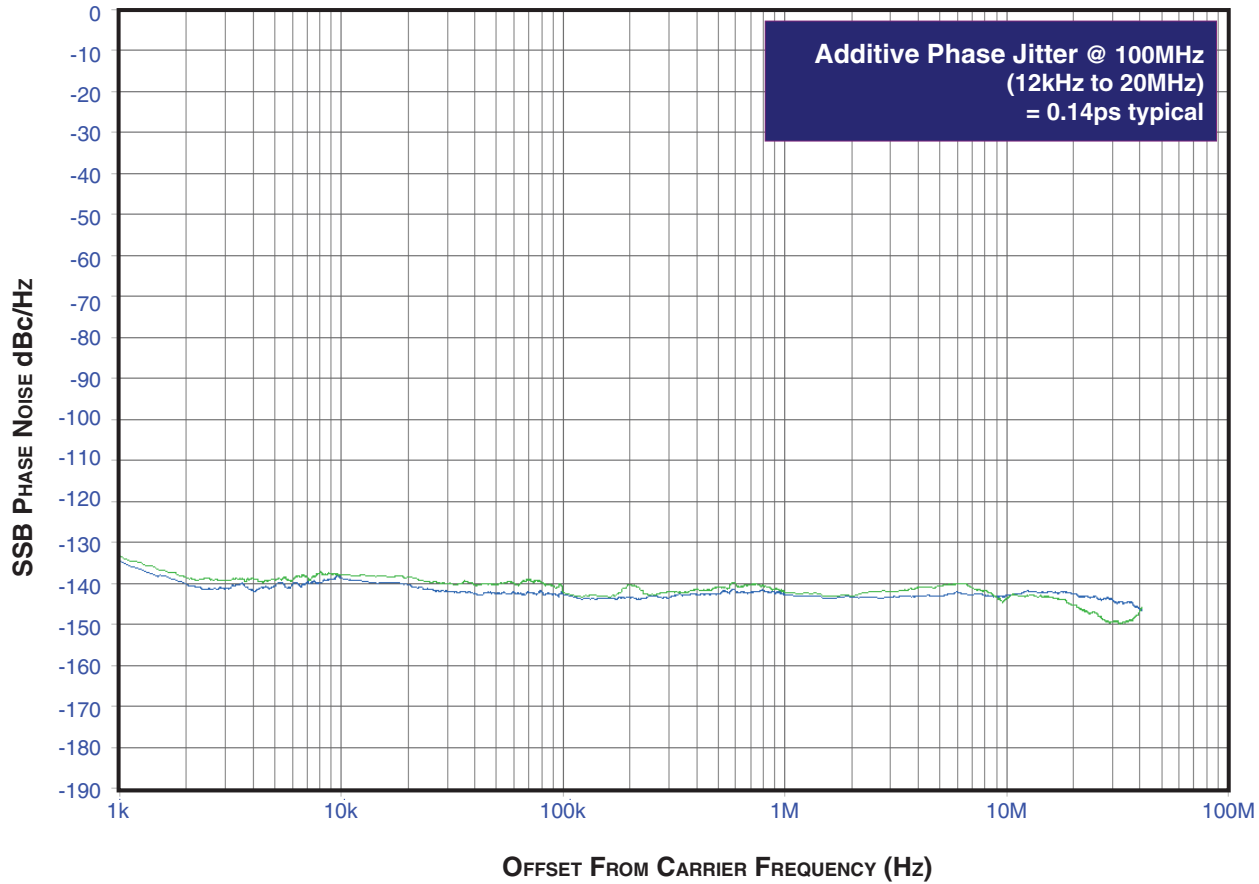
NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at  $V_{DD}/2$ .

NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.

## ADDITIVE PHASE JITTER

The spectral purity in a band at a specific offset from the fundamental compared to the power of the fundamental is called the ***dBc Phase Noise***. This value is normally expressed using a Phase noise plot and is most often the specified plot in many applications. Phase noise is defined as the ratio of the noise power present in a 1Hz band at a specified offset from the fundamental frequency to the power value of the fundamental. This ratio is expressed in decibels (dBm) or a ratio of the power in the

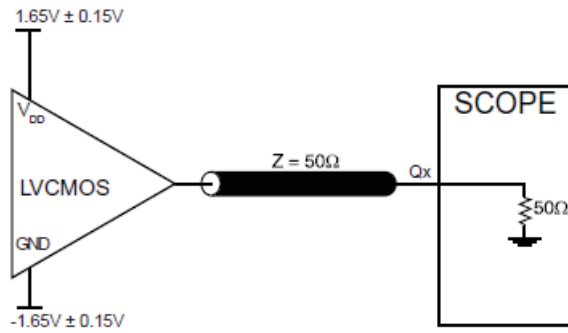
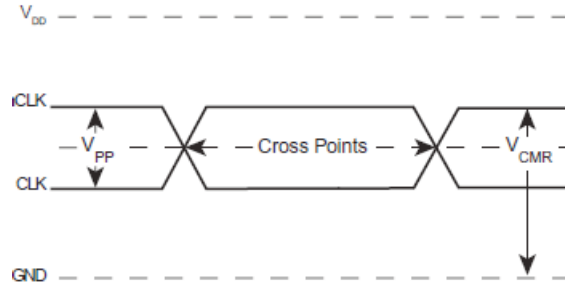
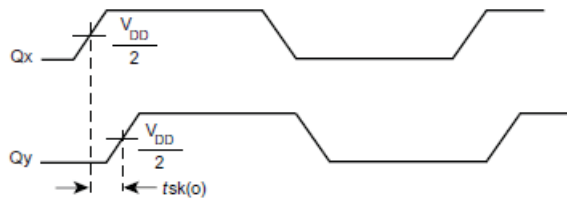
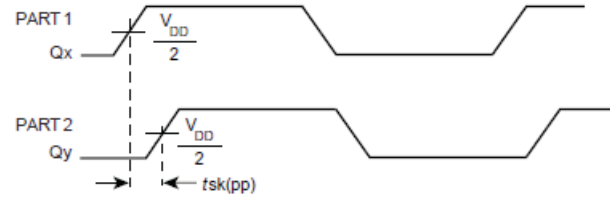
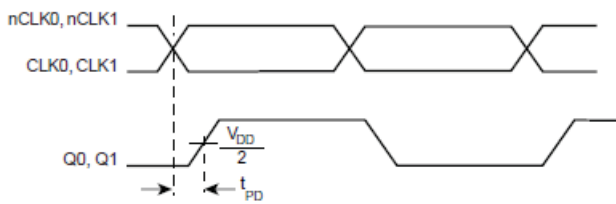
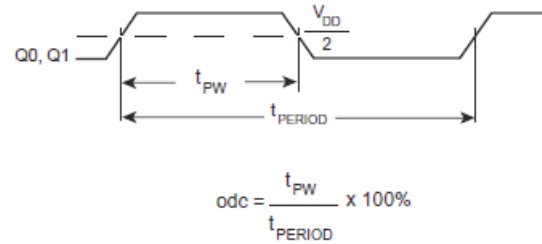
1Hz band to the power in the fundamental. When the required offset is specified, the phase noise is called a ***dBc*** value, which simply means dBm at a specified offset from the fundamental. By investigating jitter in the frequency domain, we get a better understanding of its effects on the desired application over the entire time record of the signal. It is mathematically possible to calculate an expected bit error rate given a phase noise plot.



As with most timing specifications, phase noise measurements have issues. The primary issue relates to the limitations of the equipment. Often the noise floor of the equipment is higher than the noise floor of the device. This is illustrated above. The

device meets the noise floor of what is shown, but can actually be lower. The phase noise is dependant on the input source and measurement equipment.

# PARAMETER MEASUREMENT INFORMATION


**3.3V OUTPUT LOAD AC TEST CIRCUIT**

**DIFFERENTIAL INPUT LEVEL**

**OUTPUT SKEW**

**PART-TO-PART SKEW**

**PROPAGATION DELAY**

**OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD**

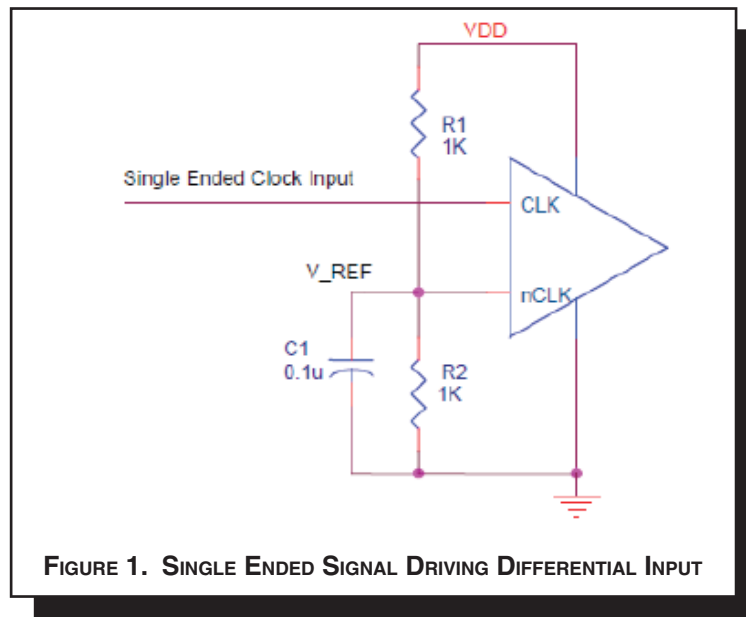
**OUTPUT RISE/FALL TIME**

## APPLICATION INFORMATION

### WIRING THE DIFFERENTIAL INPUT TO ACCEPT SINGLE ENDED LEVELS

Figure 1 shows how the differential input can be wired to accept single ended levels. The reference voltage  $V_{REF} = V_{DD}/2$  is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the input pin. The ratio

of R1 and R2 might need to be adjusted to position the  $V_{REF}$  in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and  $V_{DD} = 3.3V$ ,  $V_{REF}$  should be 1.25V and  $R2/R1 = 0.609$ .



### RECOMMENDATIONS FOR UNUSED INPUT AND OUTPUT PINS

#### INPUTS:

##### CLK/nCLK INPUT:

For applications not requiring the use of the differential input, both CLK and nCLK can be left floating. Though not required, but for additional protection, a 1k $\Omega$  resistor can be tied from CLK to ground.

#### OUTPUTS:

##### LVC MOS OUTPUT:

All unused LVC MOS output can be left floating. We recommend that there is no trace attached.





## RELIABILITY INFORMATION

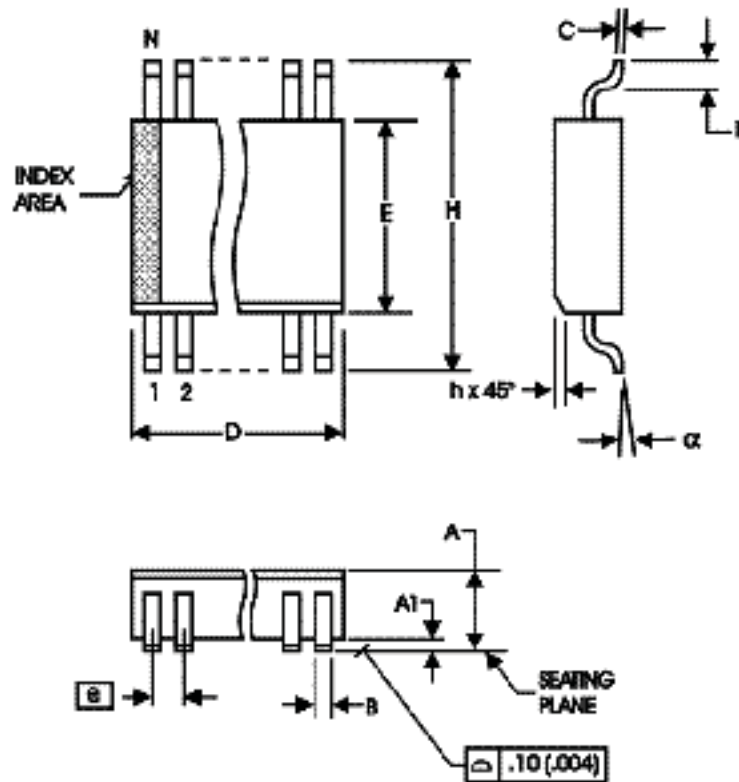
**TABLE 5.  $\theta_{JA}$  VS. AIR FLOW TABLE FOR 8 LEAD SOIC**

$\theta_{JA}$ by Velocity (Linear Feet per Minute)			
0	200	500	
Single-Layer PCB, JEDEC Standard Test Boards	153.3°C/W	128.5°C/W	115.5°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	112.7°C/W	103.3°C/W	97.1°C/W
<b>NOTE:</b> Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.			

### TRANSISTOR COUNT

The transistor count for 83023I is: 416

# PACKAGE OUTLINE - SUFFIX M FOR 8 LEAD SOIC



**TABLE 6. PACKAGE DIMENSIONS**

SYMBOL	Millimeters	
	MINIMUM	MAXIMUM
N	8	
A	1.35	1.75
A1	0.10	0.25
B	0.33	0.51
C	0.19	0.25
D	4.80	5.00
E	3.80	4.00
e	1.27 BASIC	
H	5.80	6.20
h	0.25	0.50
L	0.40	1.27
$\alpha$	0°	8°

Reference Document: JEDEC Publication 95, MS-012

**TABLE 7. ORDERING INFORMATION**

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
83023AMILF	83023AIL	8 lead "Lead Free" SOIC	Tube	-40°C to +85°C
83023AMILFT	83023AIL	8 lead "Lead Free" SOIC	Tape and Reel	-40°C to +85°C

REVISION HISTORY SHEET				
Rev	Table	Page	Description of Change	Date
A	7	11	Ordering Information Table - corrected Part/Order Number for Tape & Reel to read ICS83023AMIT from ICS83023AMI.	09/09/02
B	T2 T4 T7	1	Features Section - added Additive Phase Jitter and Lead-Free bullets.	12/12/05
		2	Pin Characteristics Table - changed $C_{IN}$ from 4pF max. to 4pF typical.	
		4	AC Characteristics Table - added Additive Phase Jitter row.	
		5	Added Additive Phase Jitter Plot.	
		7	Added Recommendations for Unused Input and Output Pins.	
B	T7	8	Added Differential Clock Input Interface.	1/18/08
		11	Ordering Information Table - added Lead-Free Part Number and Note. Update datasheet format.	
B	T7	11	Ordering information Table - added Lead-Free marking.	1/18/08
B	T7	11	Updated datasheet's header/footer with IDT from ICS.	7/29/10
		13	Removed ICS prefix from Part/Order Number column. Added Contact Page.	
B		1	Features Section - removed leaded note	4/23/14
B			Removed ICS from part numbers. Updated datasheet header and footer.	12/14/15



Corporate Headquarters  
6024 Silver Creek Valley Road  
San Jose, CA 95138 USA  
[www.IDT.com](http://www.IDT.com)

Sales  
1-800-345-7015 or 408-284-8200  
Fax: 408-284-2775  
[www.IDT.com/go/sales](http://www.IDT.com/go/sales)

Tech Support  
[www.idt.com/go/support](http://www.idt.com/go/support)

DISCLAIMER Integrated Device Technology, Inc. (IDT) reserves the right to modify the products and/or specifications described herein at any time, without notice, at IDT's sole discretion. Performance specifications and operating parameters of the described products are determined in an independent state and are not guaranteed to perform the same way when installed in customer products. The information contained herein is provided without representation or warranty of any kind, whether express or implied, including, but not limited to, the suitability of IDT's products for any particular purpose, an implied warranty of merchantability, or non-infringement of the intellectual property rights of others. This document is presented only as a guide and does not convey any license under intellectual property rights of IDT or any third parties.

IDT's products are not intended for use in applications involving extreme environmental conditions or in life support systems or similar devices where the failure or malfunction of an IDT product can be reasonably expected to significantly affect the health or safety of users. Anyone using an IDT product in such a manner does so at their own risk, absent an express, written agreement by IDT.

Integrated Device Technology, IDT and the IDT logo are trademarks or registered trademarks of IDT and its subsidiaries in the United States and other countries. Other trademarks used herein are the property of IDT or their respective third party owners.

For datasheet type definitions and a glossary of common terms, visit [www.idt.com/go/glossary](http://www.idt.com/go/glossary).

Copyright ©2015 Integrated Device Technology, Inc. All rights reserved.

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



Тел: +7 (812) 336 43 04 (многоканальный)

Email: [org@lifeelectronics.ru](mailto:org@lifeelectronics.ru)

[www.lifeelectronics.ru](http://www.lifeelectronics.ru)